

ABSTRACT

A method of making an infrared data communication module includes the steps of: forming predetermined wiring patterns on an obverse and a reverse surfaces (10a, 10b) of a substrate (1); mounting, on one of the surfaces of the substrate (1), a group of components including plural sets of light emitting elements (2) and light receiving elements (3); resin-packaging the group of components mounted on the substrate (1); and dividing the resin-packaged components to provide a plurality of infrared data communication modules (4) each of which includes a respective set of light emitting element and light receiving element. The resin-packaging step includes forming a plurality of mutually separated resin packages (4) each of which collectively seals at least two sets of light emitting elements (2) and light receiving elements (3).